Bigger, Faster, Better Resolution: Future TES Technology for SSRL Beamlines

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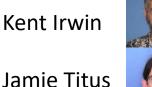
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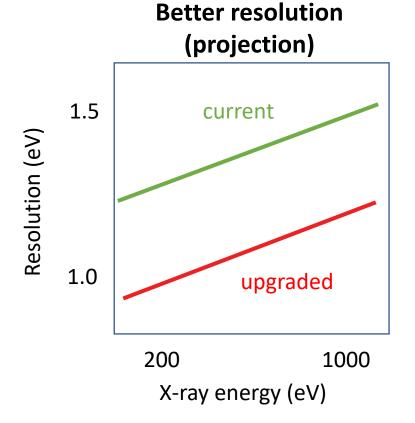


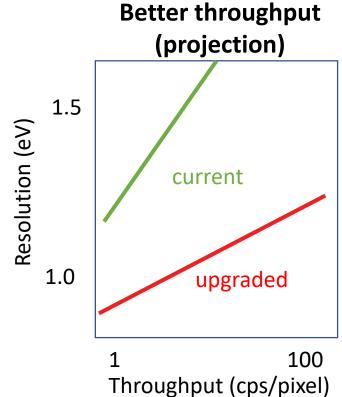




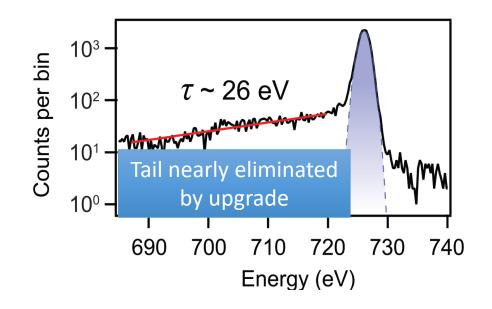


SSRL 10-1 TES Upgrades









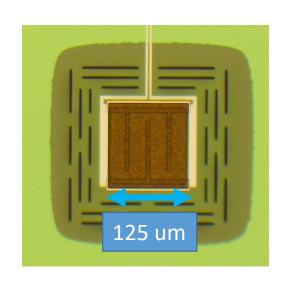
- **5.3x** effective area
- Funding from DOE Basic Energy Science
- Target install date ASAP 2021
- New TES Array + low temperature readout
- ~Better software integration, data plots available instantly

SSRL 10-1 Pixels Compared

resolution

$$\Delta E \propto \sqrt{k_B T^2 C}$$

Current

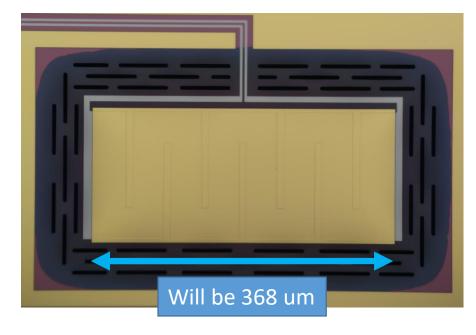




Tc ~110mK Mo/Cu Bilayer Bi plating

- Weber, 2020, Superconductor Science and Technology
- Morgan, 2017 Applied Physics Letters





Tc ~75 mK Mo/Au Bilayer

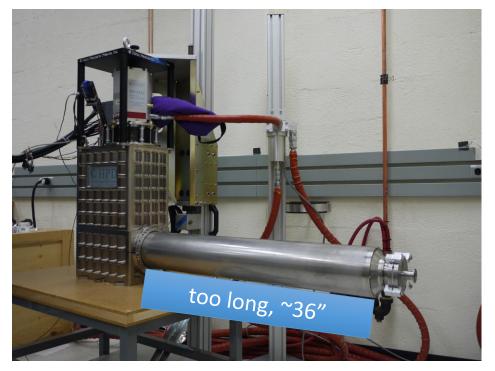
Au has:

- More area for same heat capacity
- More x-ray stopping power
- More consistent fab

SSRL 13-3 Upgrades

- Would like to follow 10-1, dependent on DOE funding
- Cryogenic improvement: Increase hold time (8->20+ hours)

13-3 now



change to match 10-1

10-1

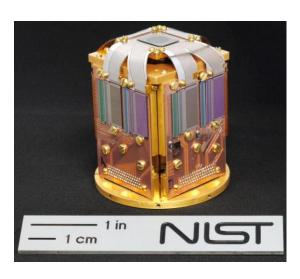


UIUC Abbamonte, APS Rodolakis, McCheseny

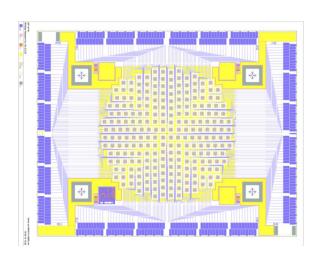
To 10k pixels for LCLS2 and beyond

soon

integral readout with alternate ucal tech

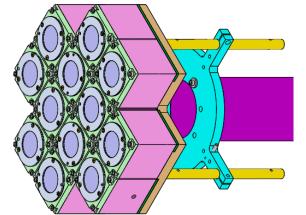


Space per wirebond $\approx 1/\sqrt{N}$

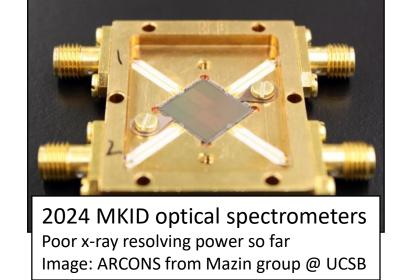




Tiled arrays







and/or

integrated 3d fabrication

